

## SYTFB020JC6S

### 2GHz Surface Mount Bandpass Filter

### **Description**

Yantel's surface mount catalog bandpass filters utilize Yantel's low loss temperature stable materials which offer small size and minimal performance variation over temperature. The catalog BPF's are offered in a variety of frequency bands, which offers a drop in solution with highly repeatable performance.

#### **Features**

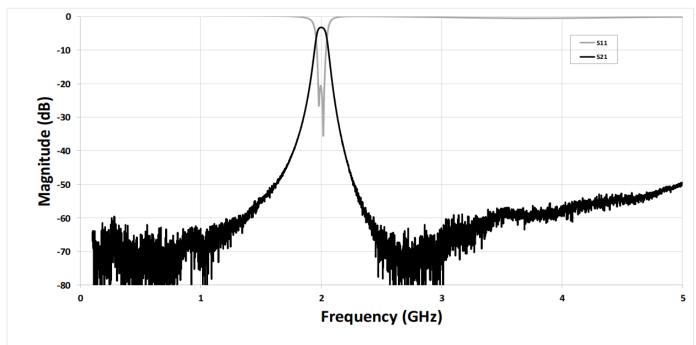
- Small Size
- Fully Shielded Component
- Solder Surface Mount Package
- Moisture Sensitivity Level: MSL1
- Frequency Stable over Temperature
- Operating & Storage Temp: -55°C to +125°C
- Characteristic Impedance: 50Ω

### Specifications\*

Parameter	Frequency Range (GHz)	Min	Тур.	Max
Insertion Loss (dB)	2.0		3.2	3.5
Return Loss (dB)		10.0	15.0	
Low Side Rejection (dB)	DC - 1.7	40.0	45.0	
High Side Rejection (dB)	2.23 - 5.0	40.0	45.0	
CW Input Power** (W)				10
$\theta_{JC} \left( \frac{^{\circ}C}{W} \right)$	7.5			
Size (L x W x H)	8.89 x 5.33 x 2.5 mm			

<sup>\*</sup>Electrical specifications based on typical probed performance at room temperature. Insertion loss shall vary ±0.5dB over temperature.

### **Typical Measured Performance**



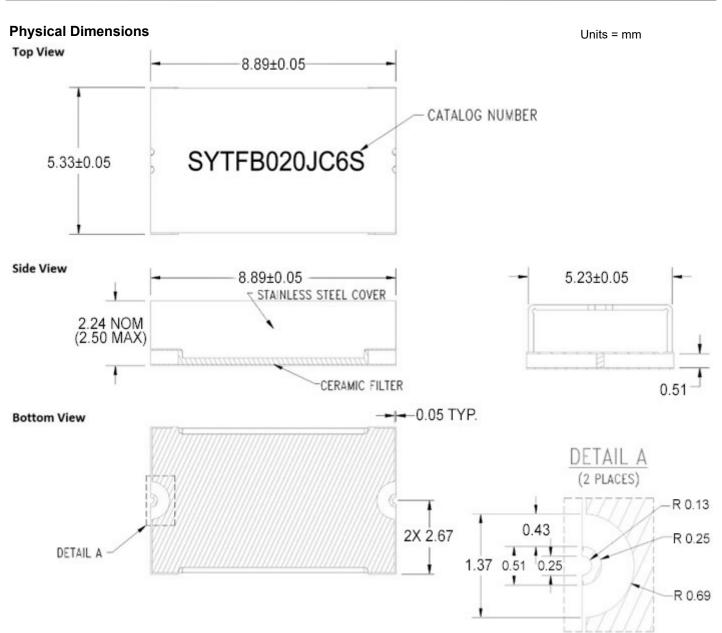
<sup>\*</sup>Typical de-embedded measured performance mounted on a connectorized test fixture. DEB is 0.254mm RO4350B with 50.00hm CPW ground traces going into the ports at room temperature

<sup>\*\*</sup>Power rating assumes the component will be mounted to a PCB with good thermally conducting ground vias as outlined in the recommended PCB layout that are connected to an adequate heat sink. Max power is based on 125°C base temperature.



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#### Notes:

1. Termination Finish:

ENIG: 76-152 μm Au over 1270 μm Ni

2. Maximum Assembly Process Temperature: 250°C

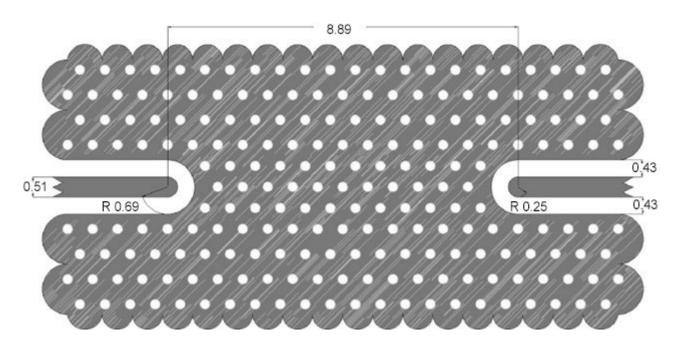
3.Dimension tolerance: ±0.05



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#### **Recommended PCB Layout**



### Notes:

Unit = mm

- $\bullet$   $50\Omega$  trace dimensions are application specific.
- Ensure adequate grounding beneath the part.